

FEATURES

- For surface mounted applications
- Glass Passivated Chip Junction
- Fast reverse recovery time
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives

VOLTAGE RANGE

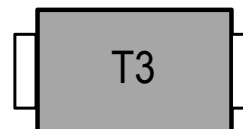
200.0 Volts

CURRENT

0.25 Ampere

MECHANICAL DATA

- * Case: Molded plastic
- * Lead: Axial leads, solderable per MIL-STD-750, method 2026
- * Polarity: Polarity symbols marked on case



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Parameter	Symbols	BAS20H	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	200	V
Maximum RMS voltage	V_{RMS}	150	V
Continuous Forward Current	I_F	250	mA
Repetitive Peak Forward Current	I_{FRM}	625	mA
Non-reptitive Peak Forward Surge Current	I_{FSM}	1 3 9	A
at 1s at 1ms at 1 us			
Total Power Dissipation	P_{tot}	500	mW
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Parameter	Symbols	BAS20H	Units
Reverse Breakdown Voltage at $I_R=100\mu A$	$V_{(BR)R}$	200	V
Maximum Forward Voltage	V_F	1.00 1.25	V
at 100 mA at 200 mA			
Maximum DC Reverse Current	I_R	0.1 100	μA
$T_a = 25\text{ }^{\circ}C$ at Rated DC Blocking Voltage $T_a = 150\text{ }^{\circ}C$			
Typical Junction Capacitance	C_j	5	pF
at $V_R=4V, f=1MHz$			
Maximum Reverse Recovery Time	t_{rr}	50	ns

RATING AND CHARACTERISTIC CURVES

Fig.1 Forward Current Derating Curve

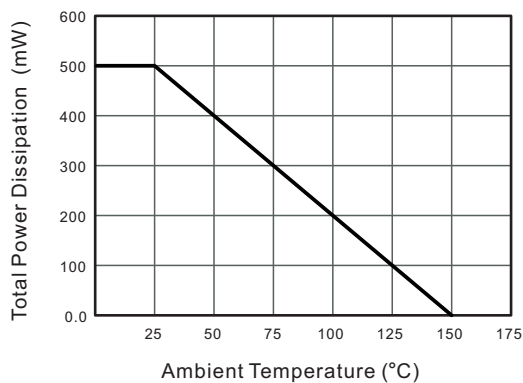


Fig.2 Typical Reverse Characteristics

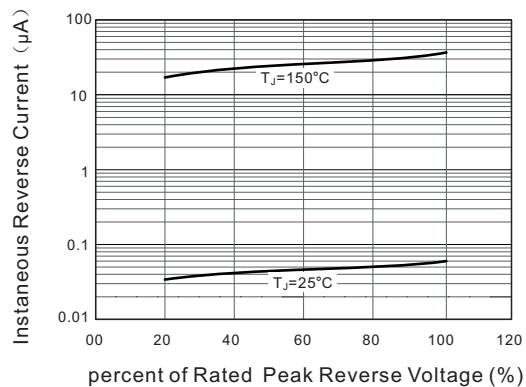


Fig.3 Typical Instantaneous Forward Characteristics

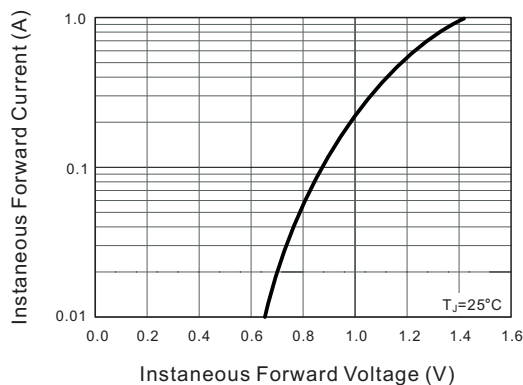
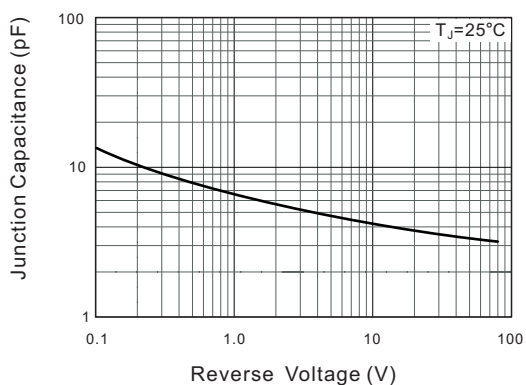
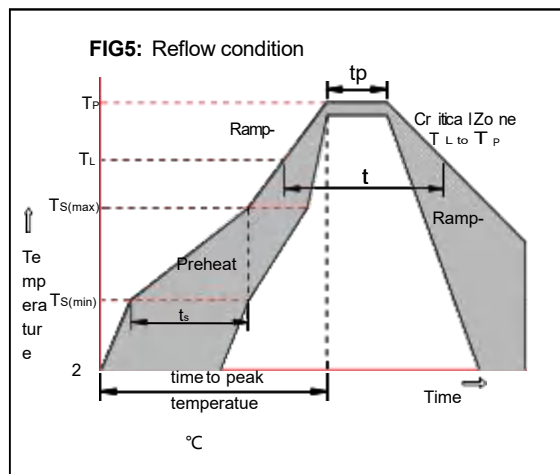


Fig.4 Typical Junction Capacitance



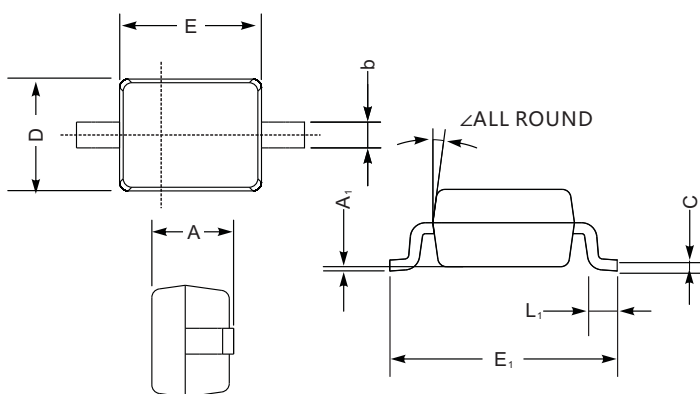
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



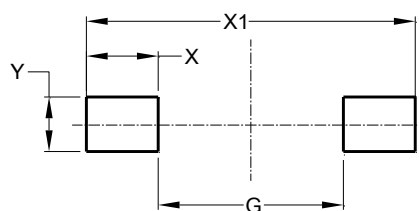
Package Dimensions & Suggested Pad Layout

SOD323



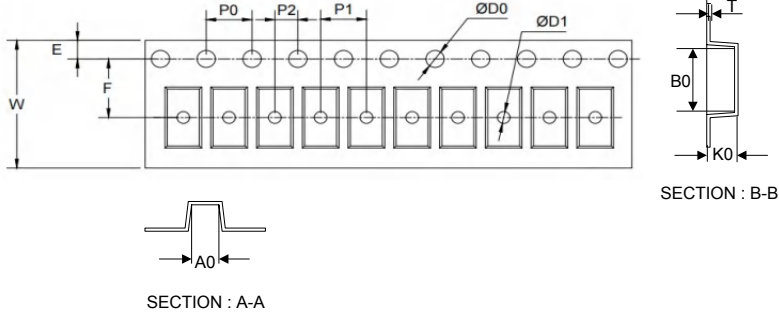
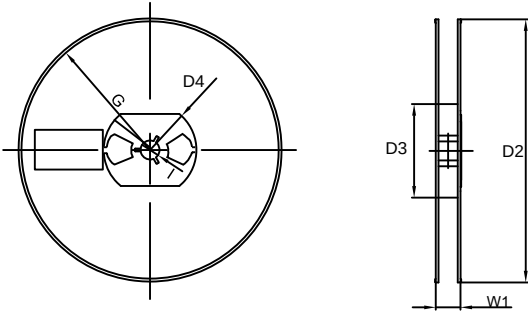
SOD-323 mechanical data

UNIT		A	C	D	E	E ₁	b	L ₁	A ₁	∠
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	63	100	9.8	7.9	—	



Dimensions	Value (in mm)
G	1.40
X	1.20
X1	3.80
Y	1.00

Tape & reel specification

Tape		Symbol	Dimension (mm)
 SECTION : A-A SECTION : B-B		P0	4.00±0.20
		P1	4.00±0.20
		P2	2.00±0.20
		D0	1.55±0.20
		D1	1.00±0.20
		E	1.55±0.25
		F	3.60±0.20
		W	8.00±0.20
		A0	2.00±0.20
		B0	3.25±0.20
		K0	1.35±0.20
		T	0.23±0.10
		D2	177.0±5.0
		D3	55Min.
		D4	R24.6±2.0
7" Reel		G	R82.0±2.0
		I	13.0±2.0
		W1	10.20±3.0
		Quantity: 3000PCS	